

R&T computing challenges for operational AI in future critical systems

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www.thalesgroup.com

**Building a future we
can all trust**

Thales 2024 key figures



83,000
employees



68 countries
A global footprint



More than **€4 bn***
* including €1,1 bn
in self-funded R&D



€20.6 bn
revenues

EMPOWER CUSTOMERS TO FACE THEIR DECISIVE MOMENTS WITH CONFIDENCE



Technologies to make the world safer, greener and more inclusive

SAFER

Protecting people from physical and cyber threats



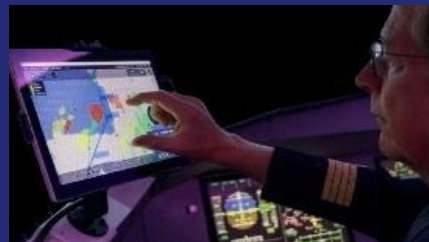
Air defence solutions for Ukraine



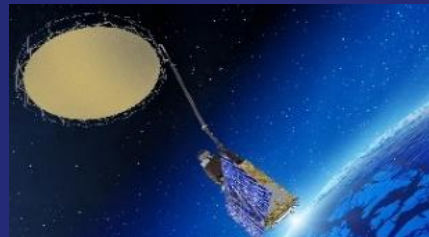
PARADE drone countermeasures system for large events

GREENER

Reducing our customers' environmental impact and building solutions to observe and understand climate phenomena



Pureflyt Flight Management System selected by Airbus



Major contributor to 5 of the 6 new Copernicus missions

MORE INCLUSIVE

Supporting universal access to basic rights (right to a legal identity, access to digital technology)



SATRIA satellite connecting 17,500 Indonesian islands



Voice Payment Card for blind and visually impaired people

Major player in Research & Development



Listed 12 times in the



Top 100
Global Innovators™
The rankings revealed.

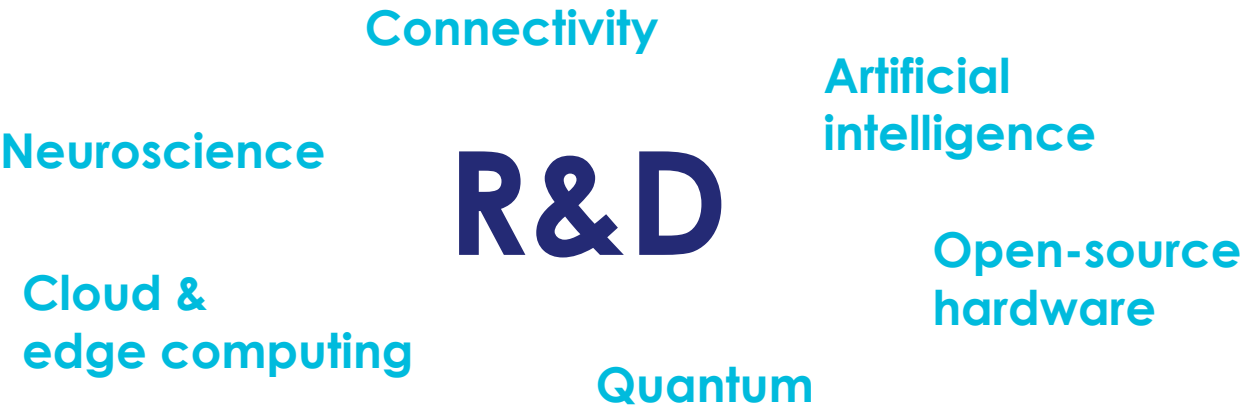


More than **40%**
of Thales employees
working in R&D

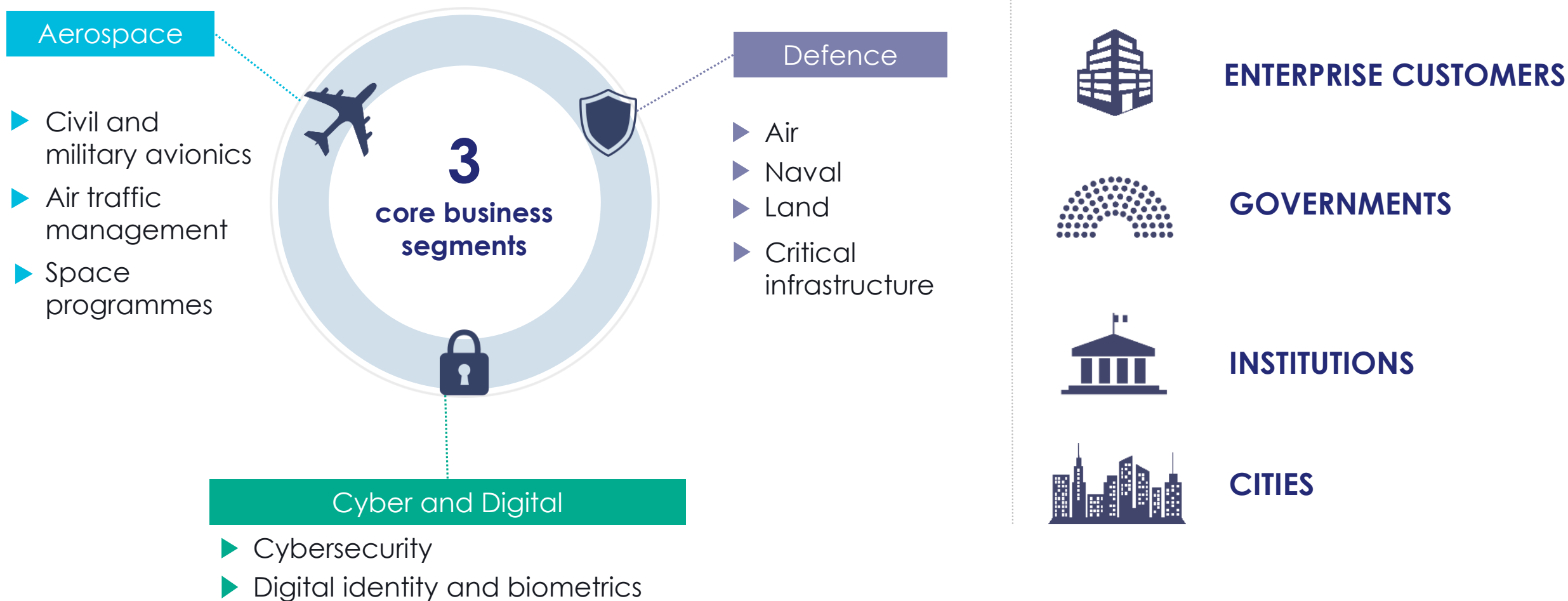


Intellectual property
portfolio including

21,000 patents



Three core business segments



Aerospace



2 million passengers use Thales **in-flight entertainment and connectivity systems** every day.

Thales Alenia Space provides

50% of the pressurised volume of the **International Space Station**.



2/3 of the world's aircraft rely on Thales equipment to **take off and land**.



With projects such as **FlytX**, Thales is developing **flight path optimisation solutions** to reduce aircraft **CO₂** emissions by 10%.

Defence



50+ countries
rely on Thales
equipment to
protect their
populations and
territorial integrity.

800,000+
Thales tactical radios
in service in **more**
than 50 countries.



Thales systems and
equipment account for
close to **25%** of
the **total value** of the
Rafale combat aircraft.

Thales is deploying **collaborative combat** solutions to
augment the **capabilities** of soldiers, vehicles and
sensors in real time.



Cyber & Digital



30,000+
companies use our
technologies to
manage identities
and secure data.

\$5 trillion
interbank fund transfers
secured every day.



300+
government
programmes for official
identity, biometrics and
law enforcement.



The **acquisition of Imperva** makes Thales one of the **world's top five cybersecurity providers** and affirms the Group's **leadership ambitions** in this market.

Artificial Intelligence: ability to process information by artificial means



Perceive rich, complex, subtle information



Learn, Adapt within a dynamic environment



Abstract to create new meanings



Reason to plan and decide

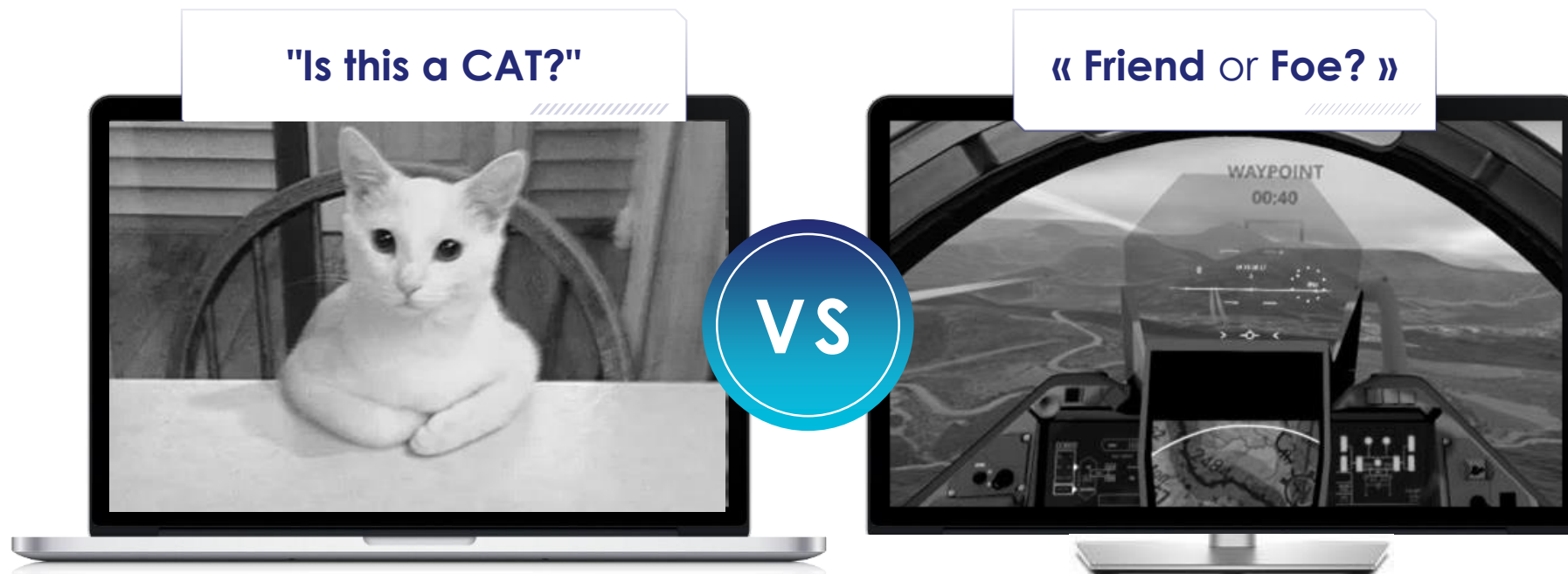


Act to achieve a rational goal



“Artificial Intelligence is the science of making machine do things that would require intelligence if done by man” **Marvin Minsky**

In critical systems, ordinary AI does not work



Impact of wrong decisions, performance threshold, technological environment



Highly specialized functions
Critical missions
Standards and ethical rules

Continuous operations
Complex systems-of-systems
AI re-training for performance

In critical systems, ordinary AI does not work

Non-critical systems

Data **availability** -
Profusion of commercial & personal data

Free data exploitation -
Open data

Persistent, cloud-based resources -
Large data centers,
unconstrained energy consumption

Error **tolerance** -
Fake results, Hacked AI



Critical systems

Data **scarcity** -
Operational & industrial data

Controlled data access -
Sovereign & classified data requiring
specific access rights

Field & edge deployment -
Limited data, power, energy, bandwidth...

No room for error -
Trustworthy AI, Cyberprotected AI

➤ Constrained deployment, development & re-training
Sovereign AI, engineering excellence, agility ◀



Artificial Intelligence for Critical Environments



A **cross-organization workforce** that **accelerates and expands AI technology integration** to provide customers operating in critical environments with robust, superior and trustworthy AI solutions



CortAlx | An international organization focused on Value & Delivery



600+
AI Experts

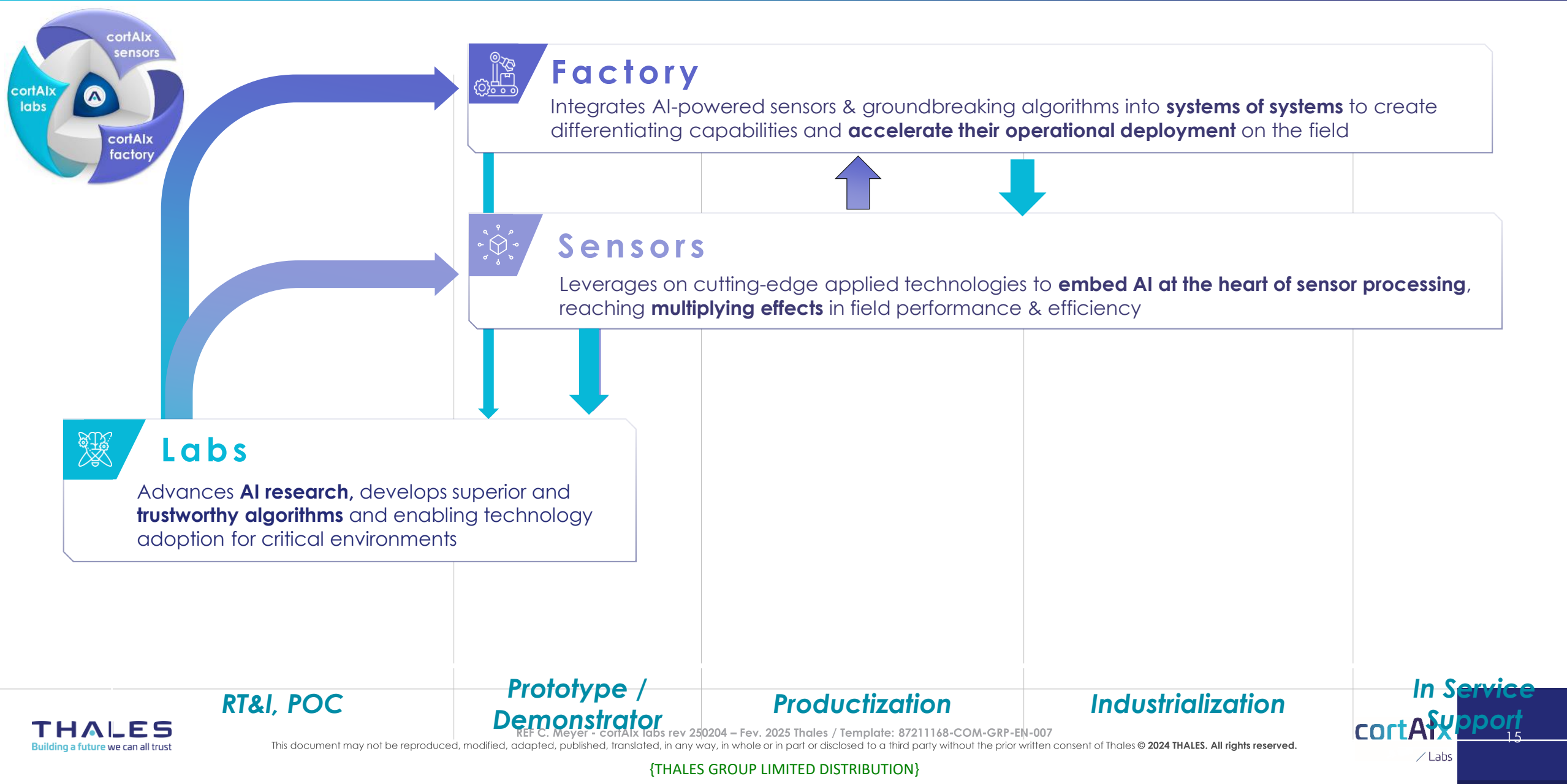


5 Sites
Sharing common
practices and
processes



200 Patents
Covering full spectrum
of AI technologies

CortAix – 3 pillars to deliver end-to-end AI superiority



cortAlx Labs is focusing on 3 RT&I Streams



AI tech. & algo.

Hybrid Knowledge & Reasoning (DL, RL, Agentic AI, GenAI, xINN...)

Decision support, planning, optimization

Modelling & Simulation (Incl. Adaptive digital twins)

Sensors' data processing

Quantum technologies (Incl. computing, sensing, networks...)



Trustworthy AI

Trustworthy AI Engineering

Trustworthy Systems and platforms

AI ↔ Cybersecurity (Inc. Friendly hackers)



AI (in) Systems

Embedded AI

Distributed AI (Incl. AI ↔ Network)

Computing Platforms/ Architectures, Edge computing

Some Key Technologies

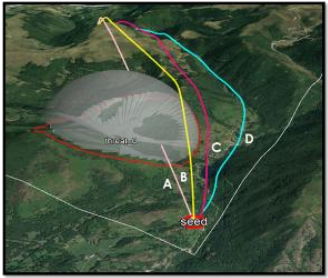
Trustable AI

- Explainable AI
- AI validation tools
- Interaction & Gen AI
- GINN (Geometries Informed NN)



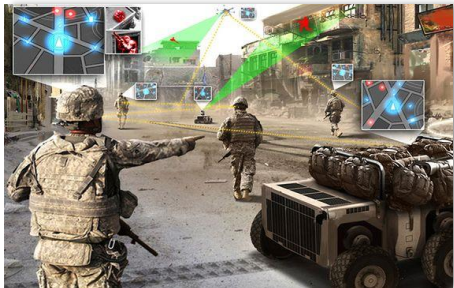
Optimization & Decision

- Optimization algorithms
- Decision aid tools



Distributed Architectures & Algorithms

- Distributed AI (Multi Agent, RL ...)
- Continuum & distributed computing
- Time Sensitive Networks



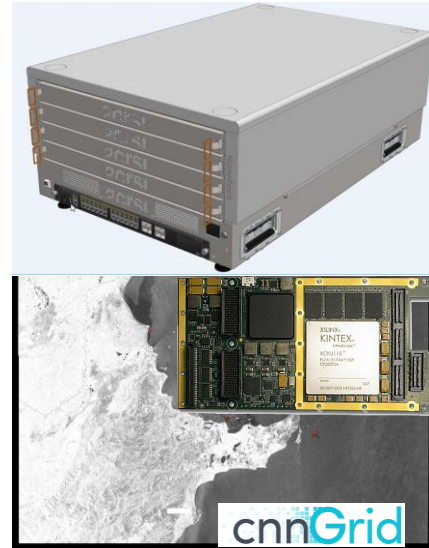
Tools & Methods for Safe and Secure

- Formal methods
- Safety analysis tools
- Cybersecurity analysis method and pen testing platform



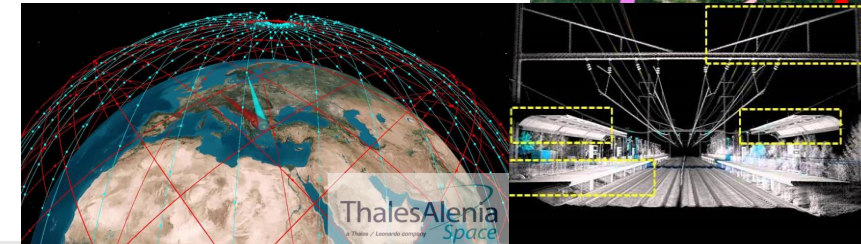
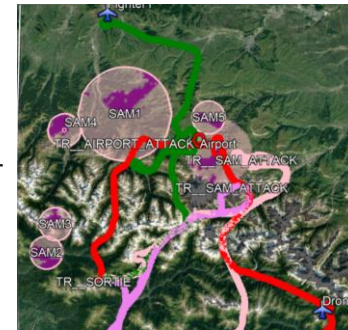
Embedded AI & Edge Computing :

- High performance computing
- Low power @ IoT & Edge
- Embedded Cyber Security
- Determinism & safety for critical system
- Neural networks & learning algorithms
- OpenHW (RISC-V & OCP)

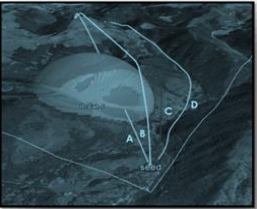

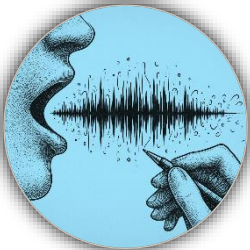






Quantum Computing

- Mastering noise impact
- Online QC



Thales cortAIx Labs cutting edge technologies – Some examples

SWARM OF DRONES	FORMAL METHODS FOR CODE VERIFICATION	AI AUGMENTED PHONY	GENERATIVE AI FOR MISSION CRITICAL SYSTEMS	EDGE COMPUTING PLATFORM FOR AI	OPEN HARDWARE: RISC-V	FRIENDLY HACKERS
 <p>COHORT: mission planning, drone coordination, distributed decision</p> <p>Learning Scout is an AI based UAVs swarm controller that has learned its complex mission through simulations.</p>	 <p>Smart card EAL7 certificate issued by ANSSI after evaluation by LETI (CESTI)</p>	 <p>Embedded AI algorithms to reduce background noise in real time and improving audio compression</p>	 <p>Generative AI components dedicated to Mission Critical Systems such as C4I.</p>	 <p>Secure, modular and energy-efficient computing solution based on open standards</p>	 <p>Thales member of the OpenHW group and RISC-V fondation. Since 5 years, strong contribution to the Open HW group on the CVA6 IP for FPGAs and ASICs</p>	 <p>Cyber for AI/Attacking and Securing AI. Ensuring trust of an AI component is essential. This covers Machine Learning, as well as Symbolic AI and Hybrid AI</p>

+ ASSETS ▶

MYRIAD

SE-Star

COHORT

Battle Box

AI for Defence Systems by THALES



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Quantum technologies (Incl. computing, sensing, networks...)



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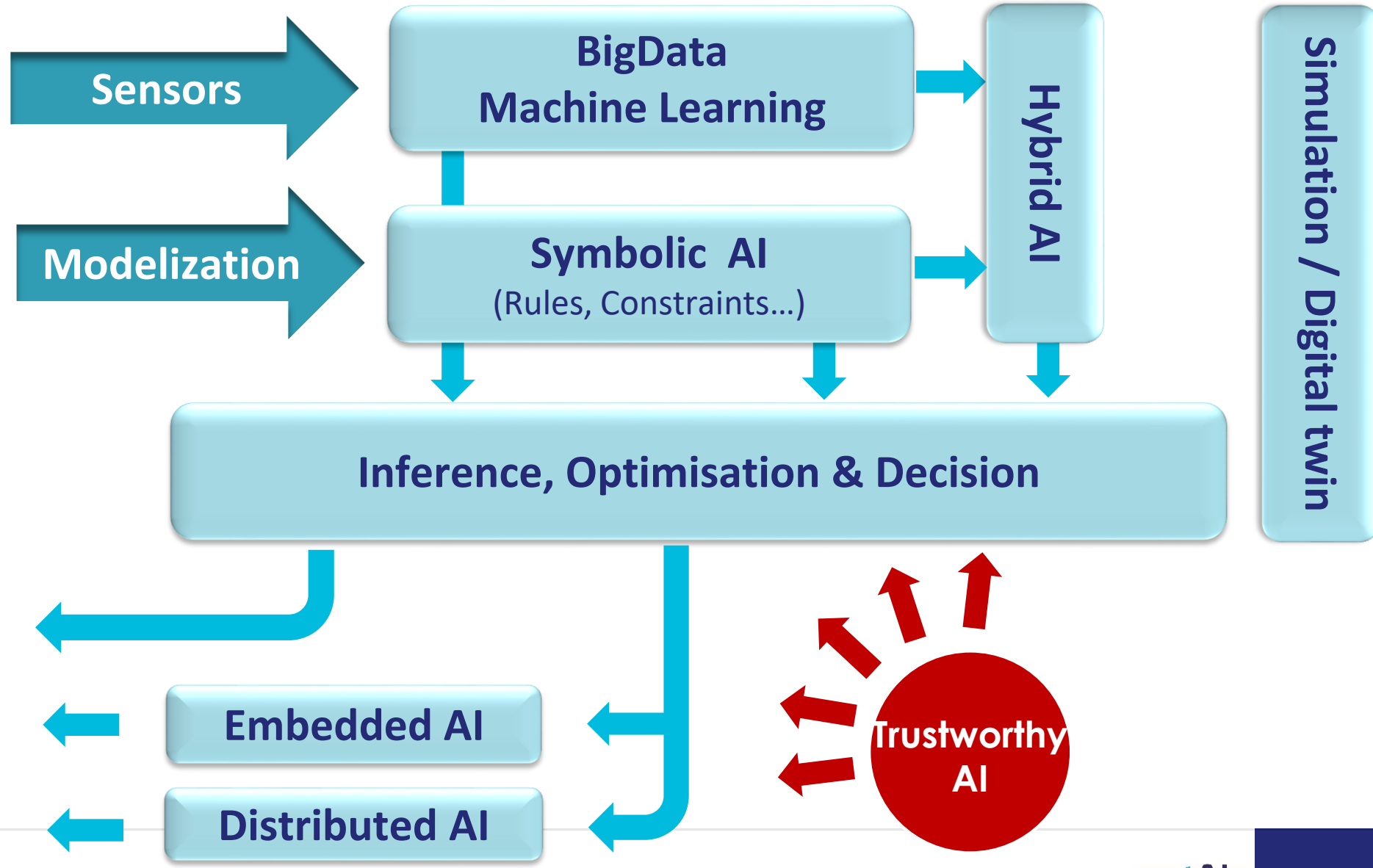
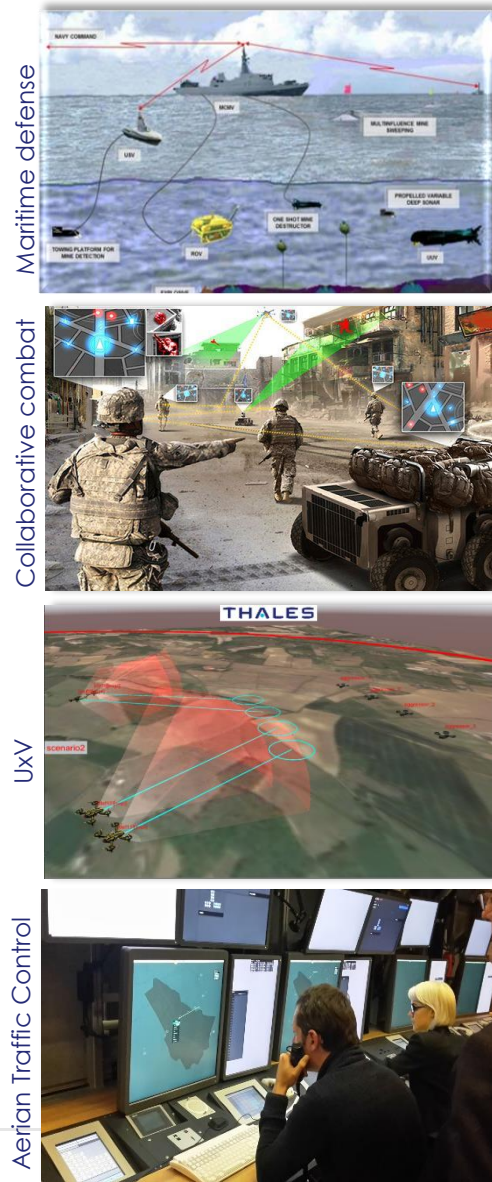
AI (in) Systems

Embedded AI

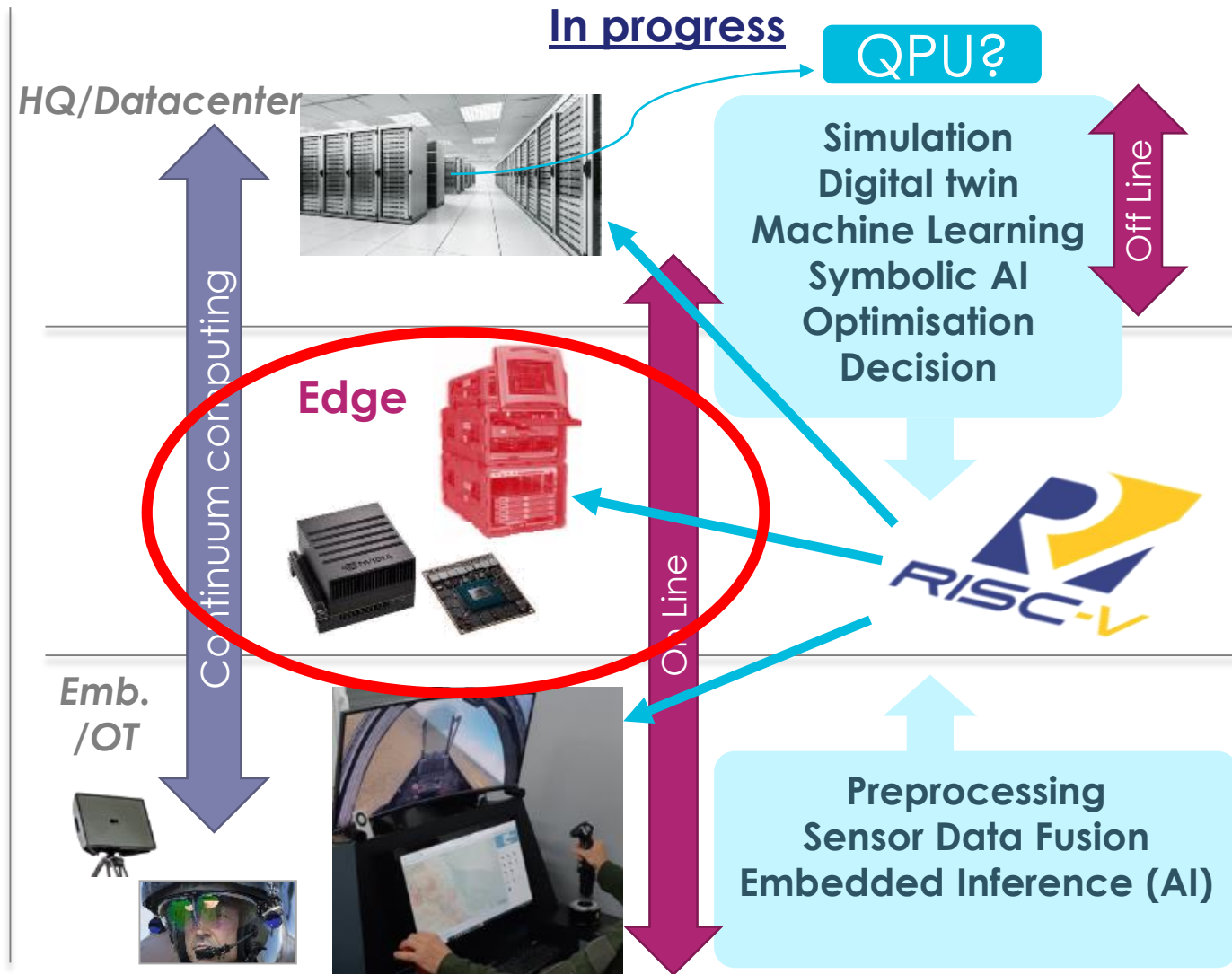
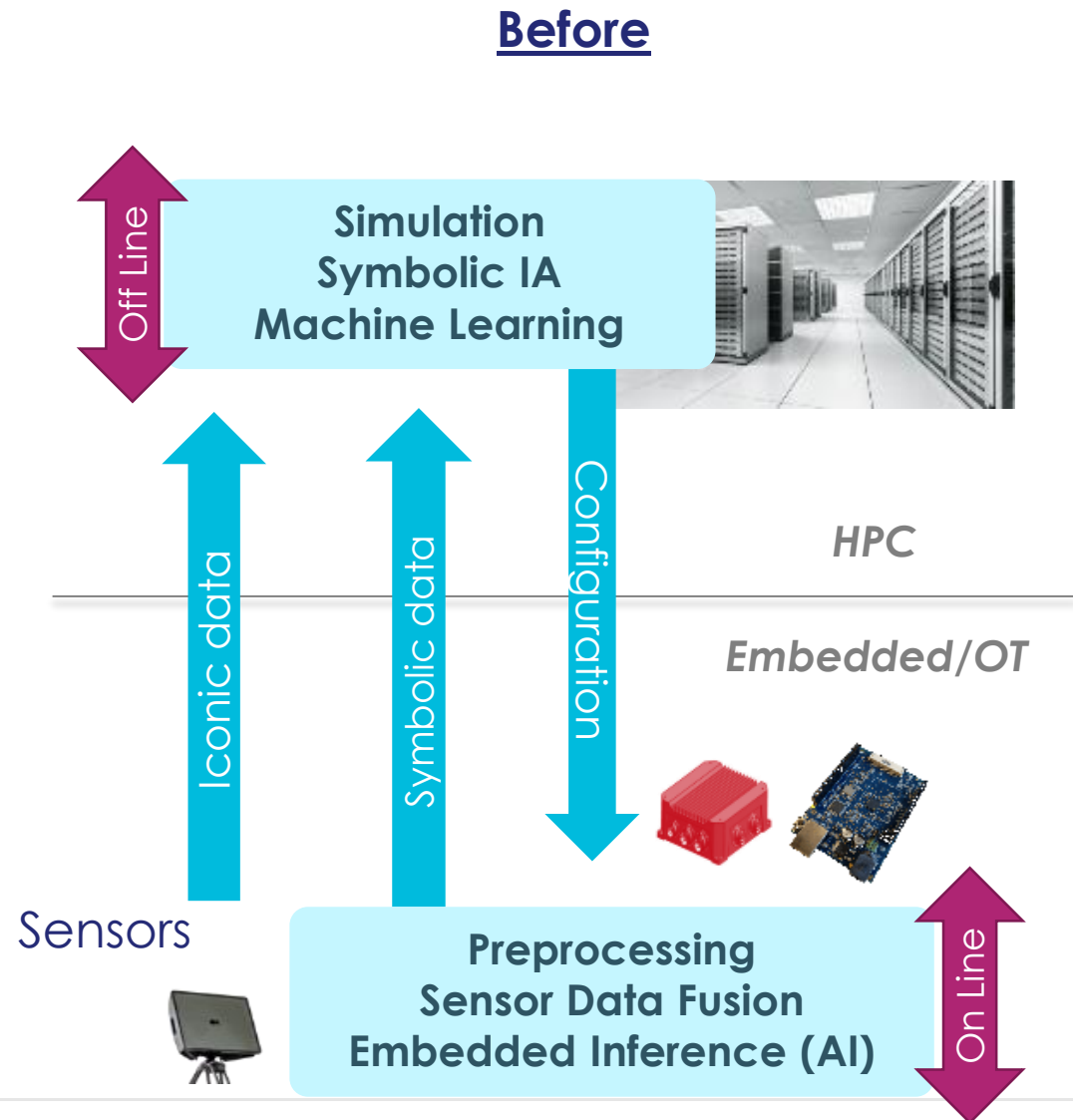
Distributed AI (Incl. AI ↔ Network)

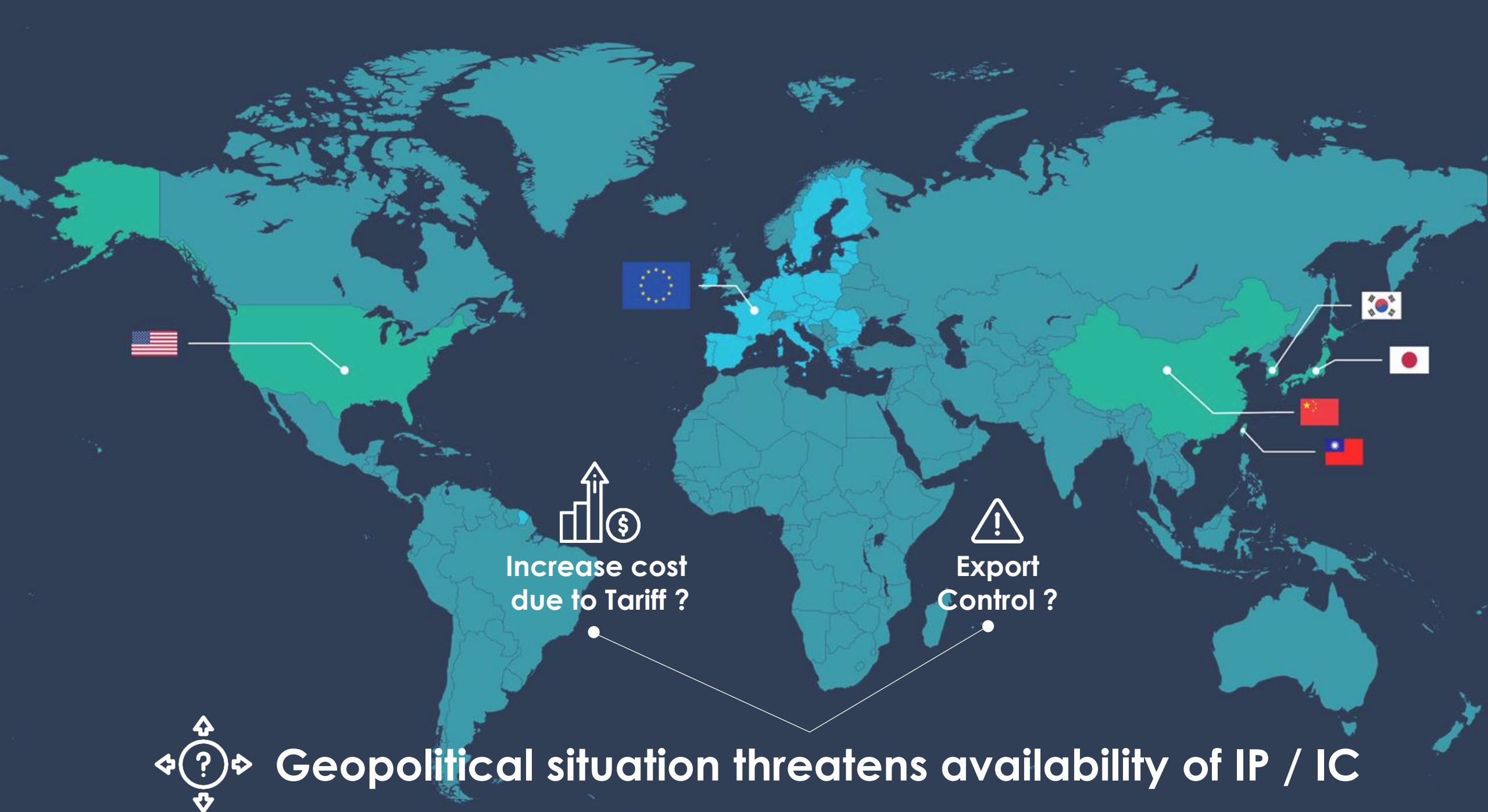
Computing Platforms/ Architectures, Edge computing

Challenges in AI algorithms



Exemple of R&T challenges for vertical IT – OT convergence





Increase cost
due to Tariff ?



Export
Control ?



Geopolitical situation threatens availability of IP / IC

Digital Sovereignty



Safe
Secure



Open
Source HW



Independent

Thales Innovation

Industrial Grade CVA6 μ Controller released as Open Source

- ▶ **CV32A60X**: Low area and High performance CVA6 Core
- ▶ 100% Verified, Sovereign, ready for integration into silicon products (TRL5) !
- ▶ ***Focus on your Added Value IP / Differentiator, CVA6 comes as a commodity***



Axelera Metis
Inference time: 2.31ms

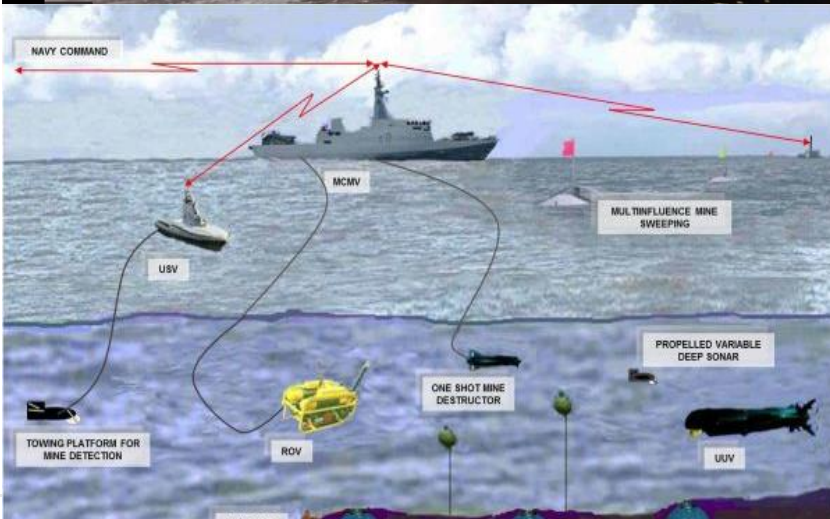
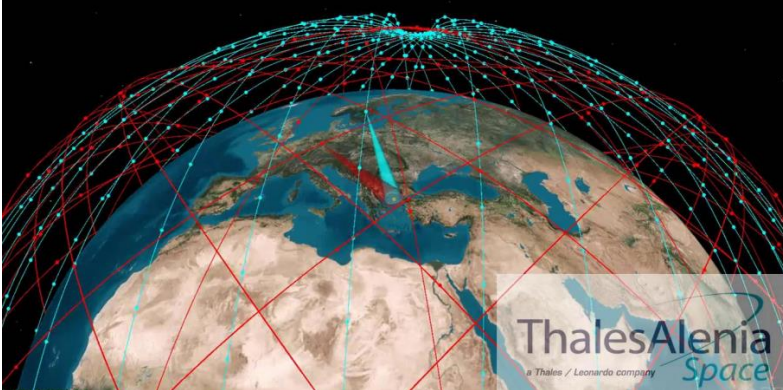


DDG-79-USS-Oscar-Austin 0.98

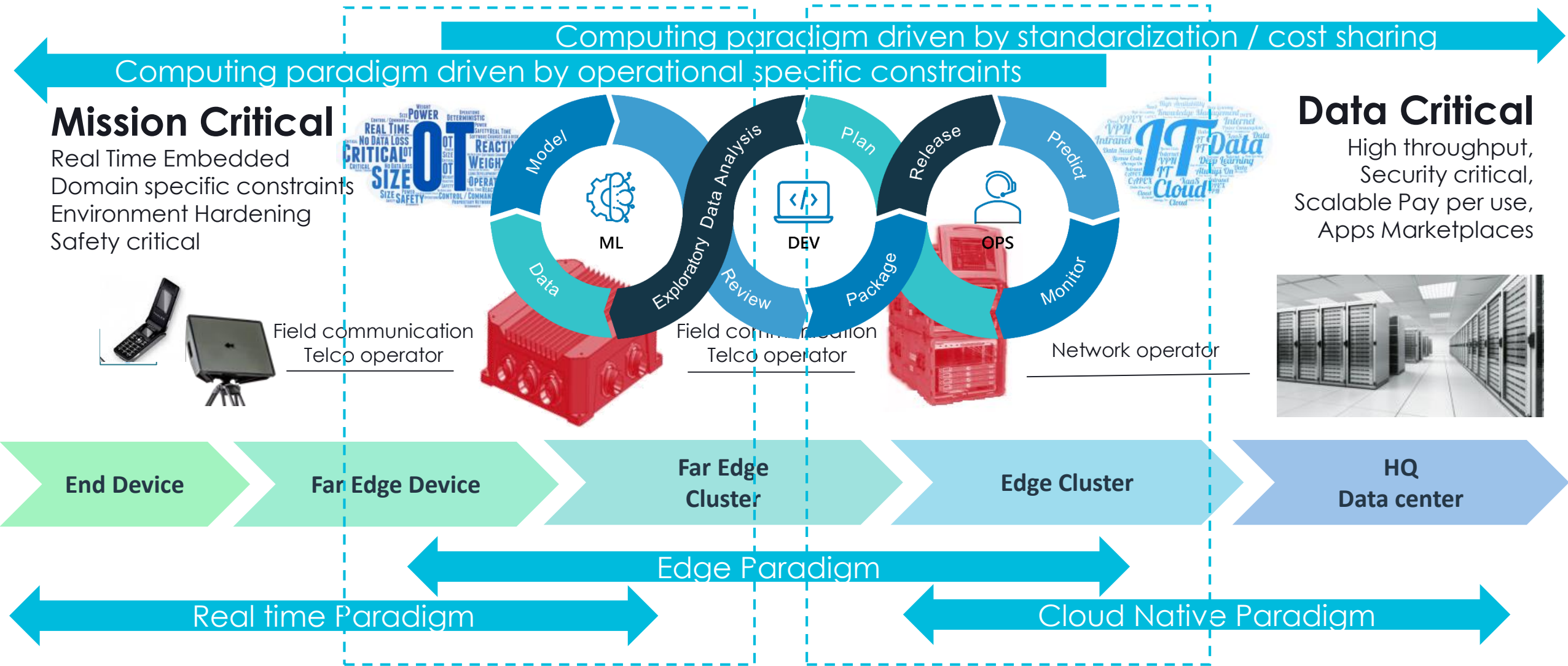


CONTINUOUS & TRUSTABLE COMPUTING SOLUTIONS

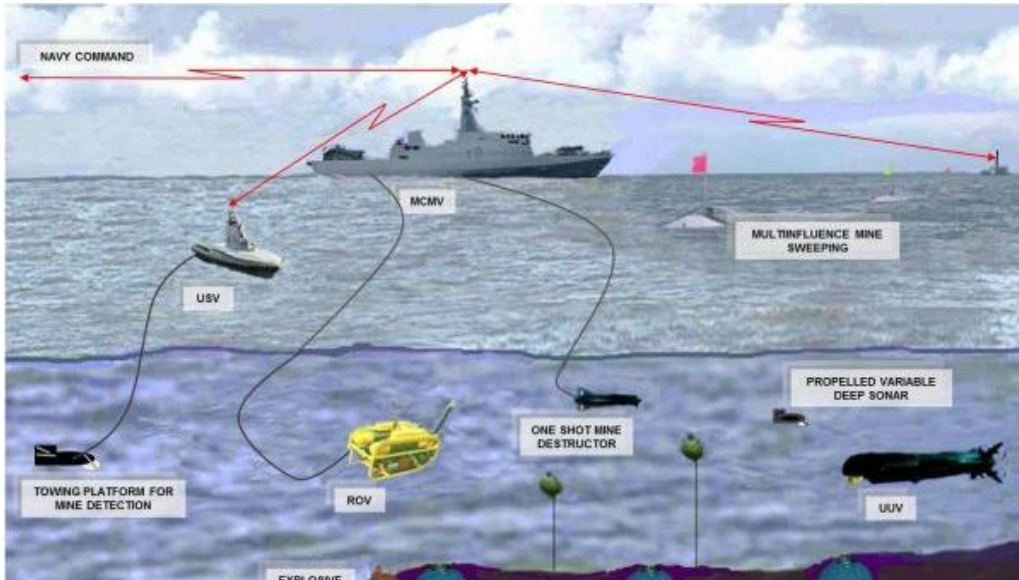
- Cloud-Edge-IoT
- Interconnection
- Autonomy
- Cybersecurity
- Low Power
- Safety



Critical Decision Chain & IT/OT convergence



New Challenges for the Edge

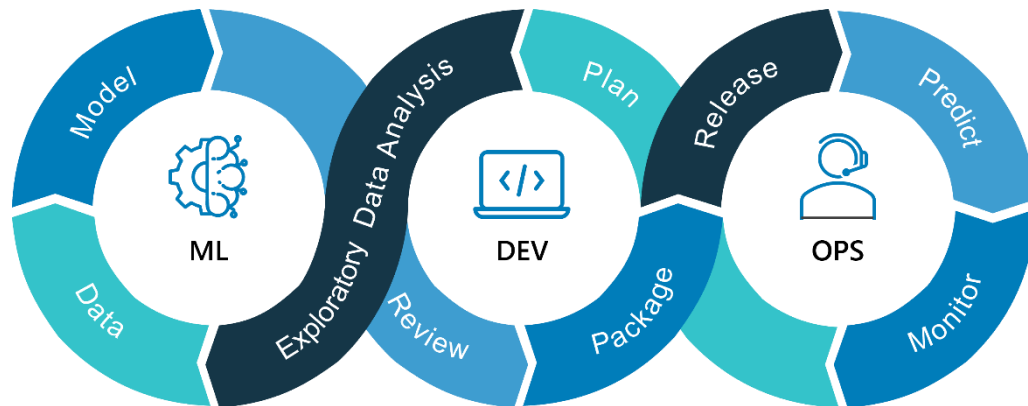


✓ Level of AI :

- ▶ Engineering Level : The Edge must collect the data (Off line MLOPS)
- ▶ On Board off line applications : MLDEVOPS abilities at the Edge (Edge Cluster)
- ▶ On Board In line applications : CI/CD-MLDEVOPS abilities at the Edge (Far Edge + Edge Cluster)

✓ Level of Infrastructure :

- ▶ OSS SW stack
- ▶ Containerized applications
- ▶ Continuum in 2D
- ▶ Determinism for some applications (Sensor driven)
- ▶ Cybersecurity at all levels
- ▶ SWAP optimization
- ▶ Continuous Integration / Continuous Deployment

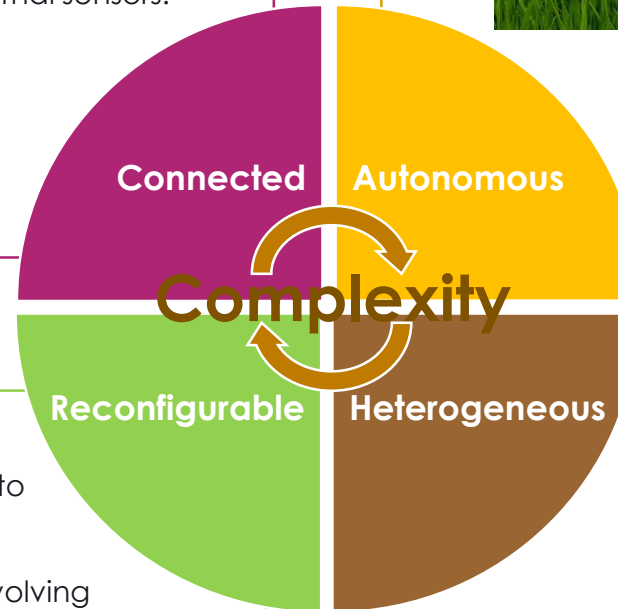


Technical Innovation Challenging Critical Real-Time EDGE systems

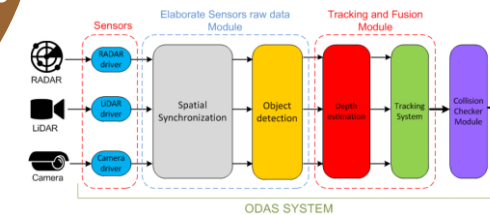
- **Connected** real-time systems will be included into **heterogeneous infrastructures**, where the software running into its internal computers is connected to other computers, databases, web interfaces, or even to external sensors.



- **Autonomous** systems lead to a dramatically increasing demand of **connectivity** capacities and processing power that can only be provided by **heterogeneous** computing platforms.



- **Dynamic** reconfiguration is key to respond to needs of autonomy
- Multiple **static** configurations involving **heterogeneous** SW functions and suppliers
- On-demand **upgrades** and **customization** is the key to the future of the **connectivity**



- Heterogeneous **functions domains** on heterogeneous **hardware** architecture provided by heterogeneous **parties** and operating in heterogeneous **environnements**

Modular Open HW approach in order to optimize the energy efficiency

> Design of a modular software-defined Edge computer (ODYSSAI)

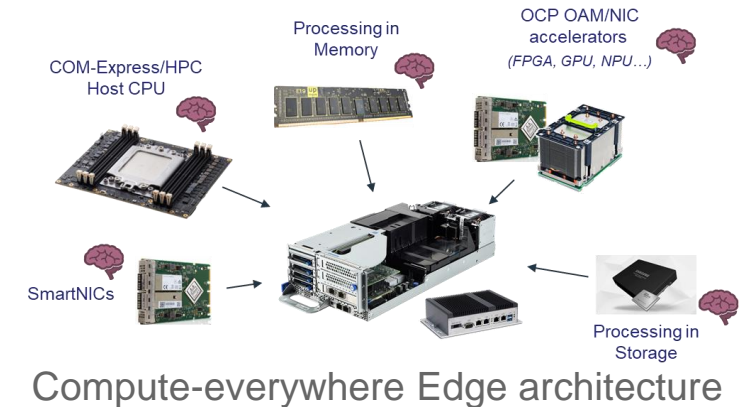
- › Use of existing open standards (OCP, interfaces, interoperability, firmware, power, security, etc.),
- › Integration of heterogeneous and energy-efficient computing solutions (either low cost),
- › High modularity and scalability capabilities (sustainability),
- › Leverage IT/OT convergence,
- › Chiplet architectures with UCle interfaces, ...

> Leverage the compute-everywhere architecture

- › Compute where the data are stored (NearMC, InMC),
- › Compute during data transfers (DPU).


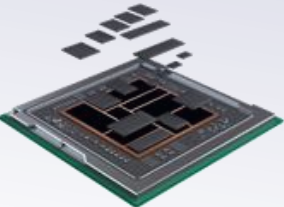
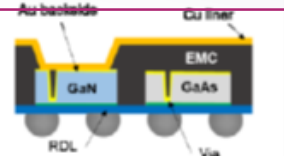
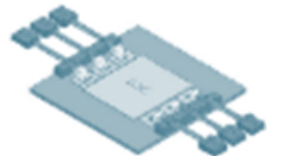
> Use of embedded computers instead of IT ones

- › eGPUs vs IT GPU accelerators,
- › ARM vs x86 cores, RISC-V tomorrow.

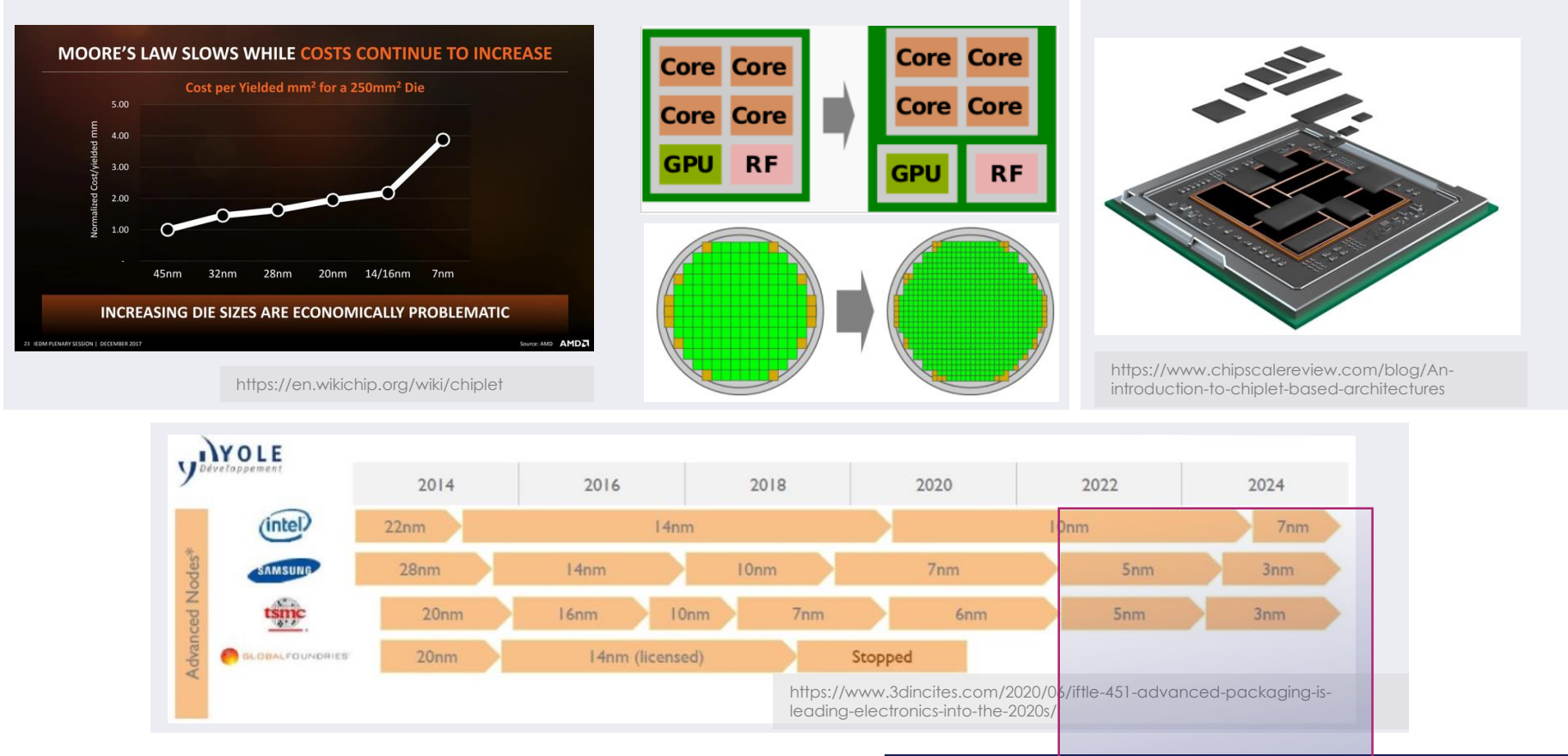


Opening up to European Suppliers (SMEs, start-ups, etc.) and then creating an European Edge Ecosystem

Motivation: evolutions expected to 2030

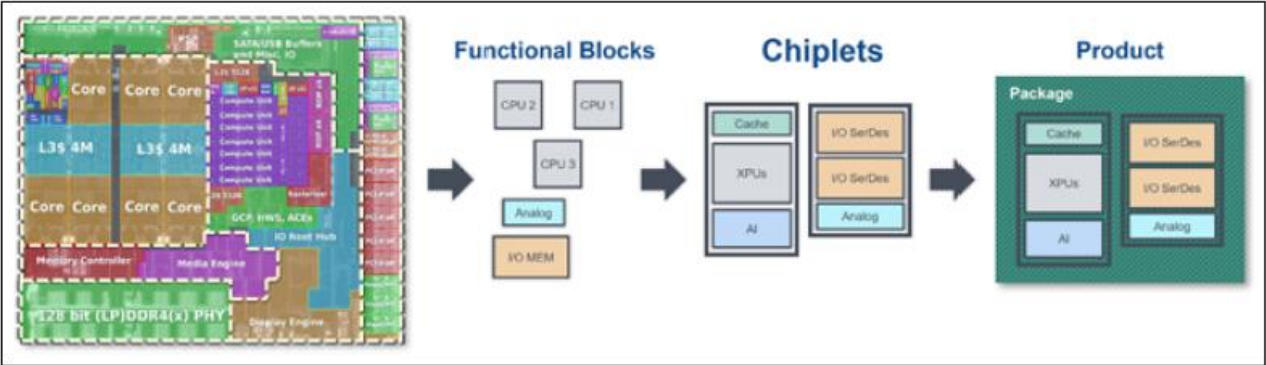
	Expected	Why
	MCM > SiP	More integration
	SoC > Chiplets	Exponential increasing costs of design and production for the latest Si nodes
	More RDL	Frequency increasing
	More optical interfaces	Sensors, Free space communications and data transmission

Heterogeneous integration > Chiplets



HI mandatory to use the latest Si nodes technologies

Heterogeneous integration > Modularization



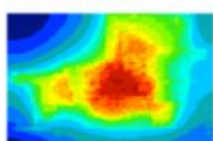
Chiplets Need Architected, Fully Specified Interfaces

Mechanical



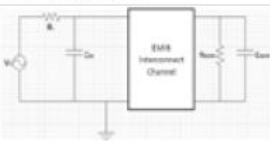
- Bump and wire sizes
- Bonding footprint
- xyz constraints

Thermal



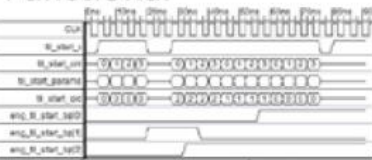
- Thermal/temperature characteristics and constraints

Electrical



- Power delivery
- Noise margin
- Capacitance

Functional

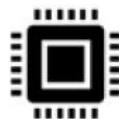


- Data/transaction specifications
- Mgmt: power, security, debug, etc.
- Configuration & statistics
- Manufacturing test access

Which support
Generational Compatibility



All enabled by off-the-shelf
Tools/Flows/Methods and
HW/SW Building Blocks



... to support industry scale systematic reuse

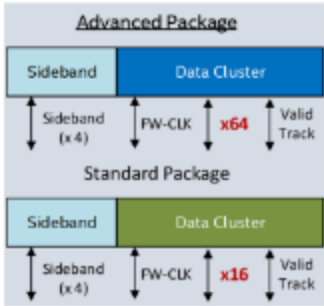


New HPC architectures >
Modular Approach
Commercial Chiplets?

Heterogeneous integration > Interconnects

Current Chiplet-based Interconnects				
Company	Intel	Intel	TSMC	OCP ODSA
Package	EMIB	EMIB/COI	CoWoS	MCP
Interconnect	AB Gen1	MDIO Gen1	UPINCON	Dow Turbo (3 slices)
Data Rate	2 GT/s	5.4 GT/s	8 GT/s	16 GT/s
Shoreline BW Density	504 Gbps/mm	1600 Gbps/mm	536 Gbps/mm	1280 Gbps/mm
PHY Power	0.85 pJ/bit	0.5 pJ/bit	0.5 pJ/bit	0.7 pJ/bit (14nm measured) 0.5 pJ/bit (7nm estimate)
Areal I/O Density	150 Gbps/mm ²	198 Gbps/mm ²	158 Gbps/mm ²	146 Gbps/mm ²

Other solutions
Chiplet
integration
solutions



https://www.uciexpress.org/_files/ugd/0c1418_c5970a68ab214ffc97fab16d11581449.pdf

> OCP / ODSA

<https://www.opencompute.org/projects/open-domain-specific-architecture>

FINE LINE STRUCTURING
Starting with 5µm Line/Space

SMALL VIA FORMATION
CO2 and UV Laser Systems

Finer design structures with 2µm Line/Space on the Roadmap

µVia diameter 10µm and smaller for z-interconnection

Standardized interfaces (ODAS / UCIe)

> UCIe

- The physical layer supports up to 32 GT/s
 - with 16 to 64 lanes
 - uses a 256 byte Flow Control Unit (FLIT) for data, similar to PCIe 6.0

Shorter signal paths allow the links to have 20× better I/O performance and power consumption (~0.5 pJ per bit) comparing to typical PCIe SerDes

- with bandwidth density up to 1.35 TByte/s per mm² for a common bump pitch of 45 µm
- 3.24× higher density with a bump pitch of 25 µm

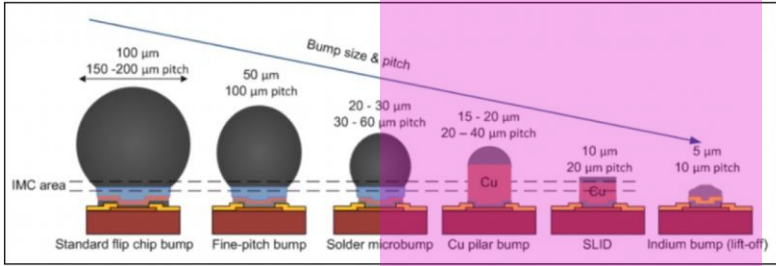
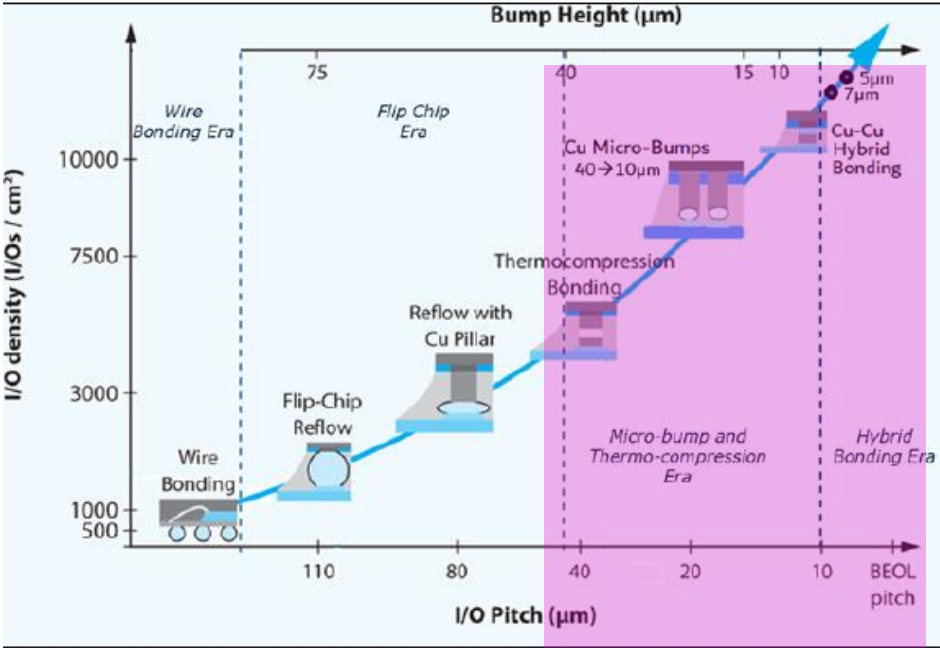


Figure 1: Evolution of bump size and pitch. Image courtesy of T. Tick and S. Vahanen [1]

Advanced integration (pitch below 50 µm)

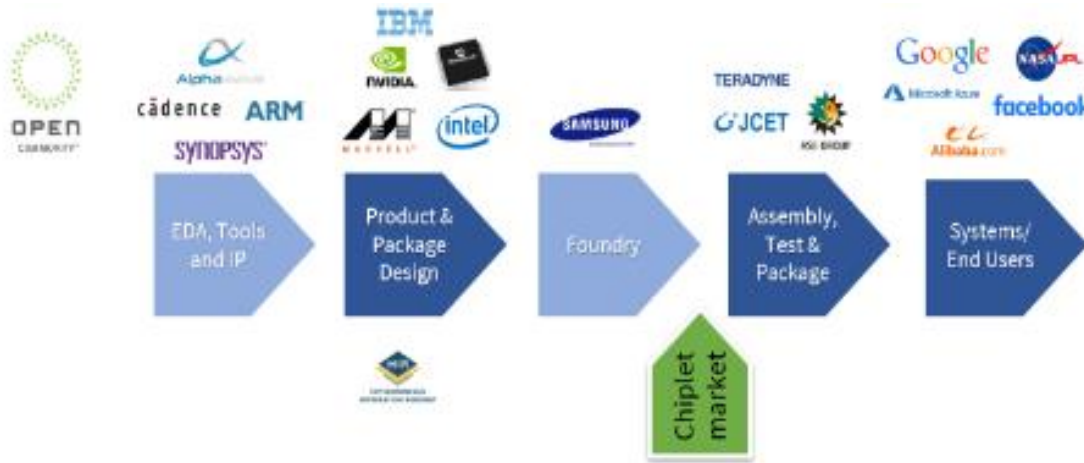
Heterogeneous Integration fo ADHP

> Datacenter, High-Computing will probably benefit from Chiplet architecture

- ▶ It allows modular and scalable designs
- ▶ It is well suited for digital computing applications (CPU, GPU, APU, HBM) > Competitive solution for latest nodes

> Aerospace (including constellations), Defense and High Performance (including ADAS) applications have specificities

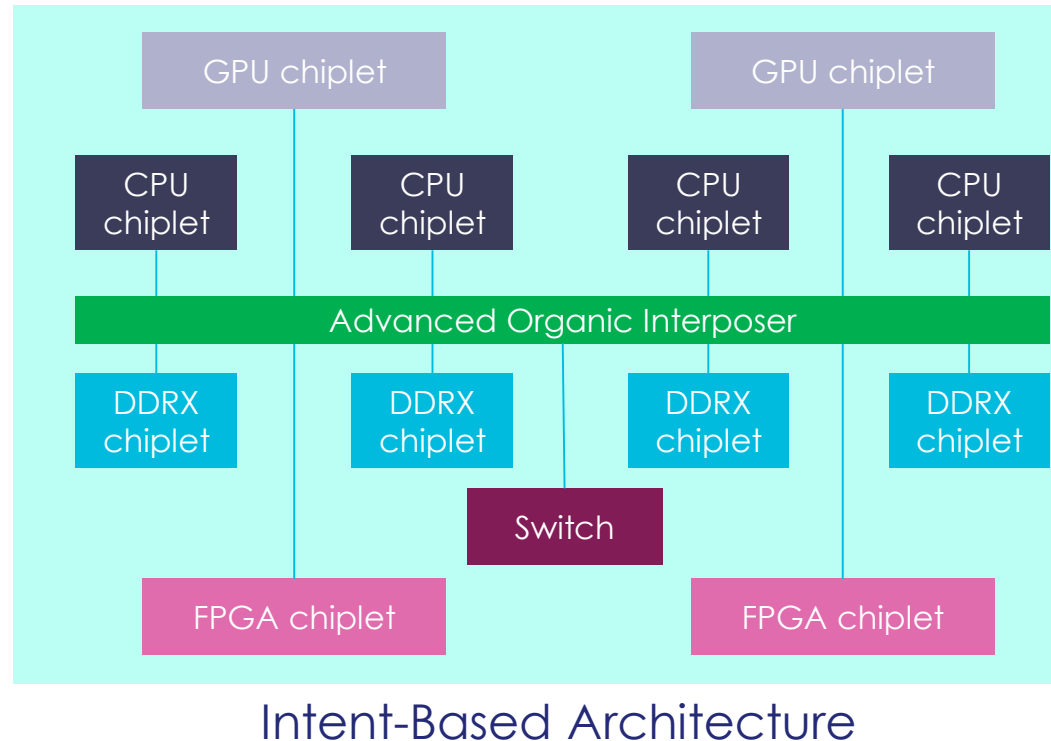
- ▶ High-reliability
- ▶ Harsh environment
- ▶ Long mission profile
- ▶ + ... medium to low volume



**Will be there a Heterogeneous Integration Supply Chain?
Is Chiplet Integration possible in medium to low volume?**

Heterogeneous integration > Industrial, Safety, Security and Reliability

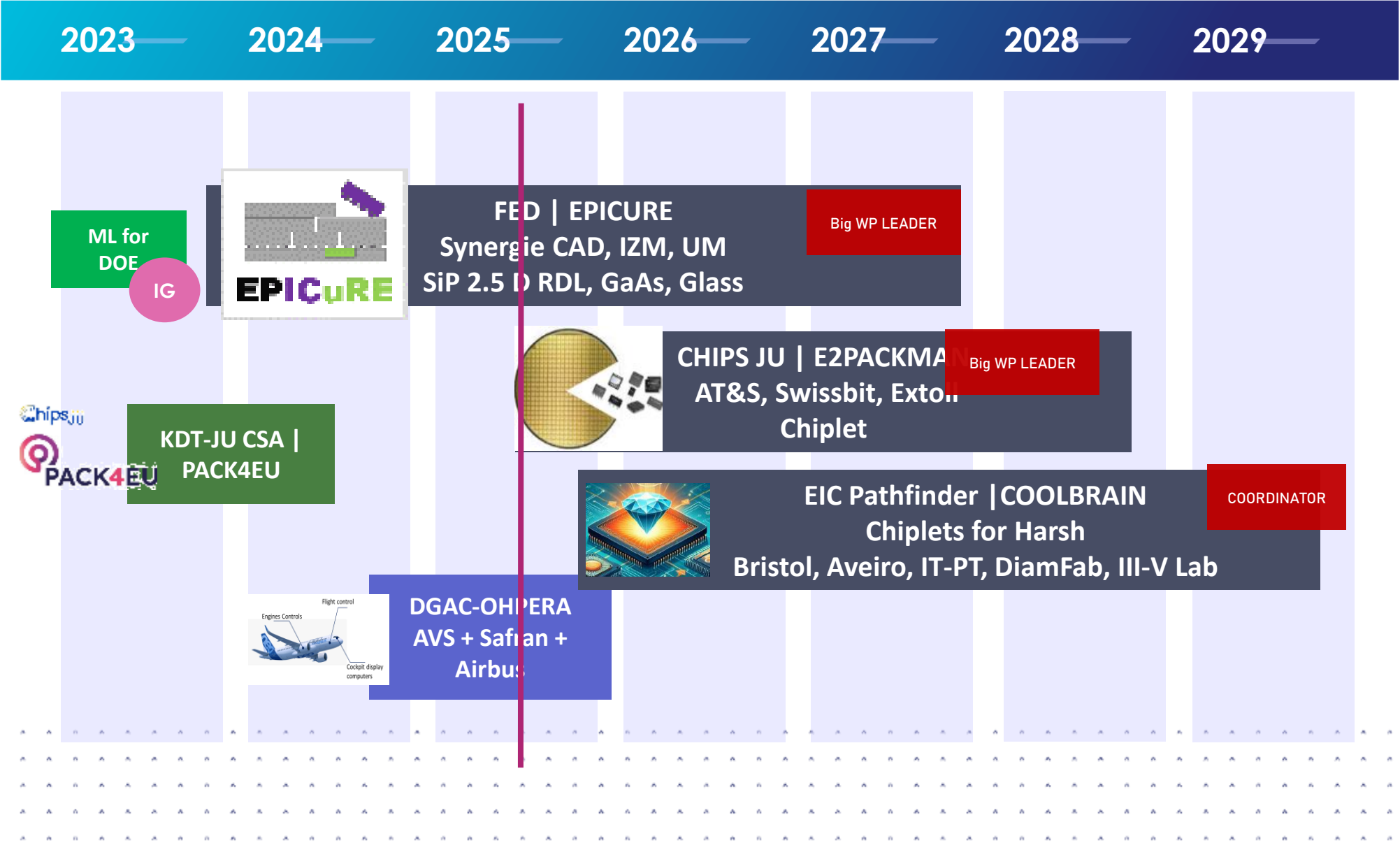
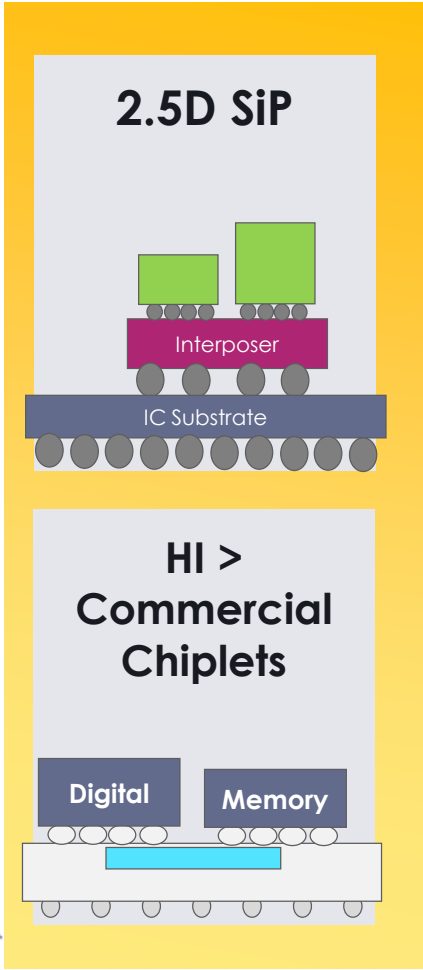
**Next
generation of
Avionics
computing
including
chiplets**



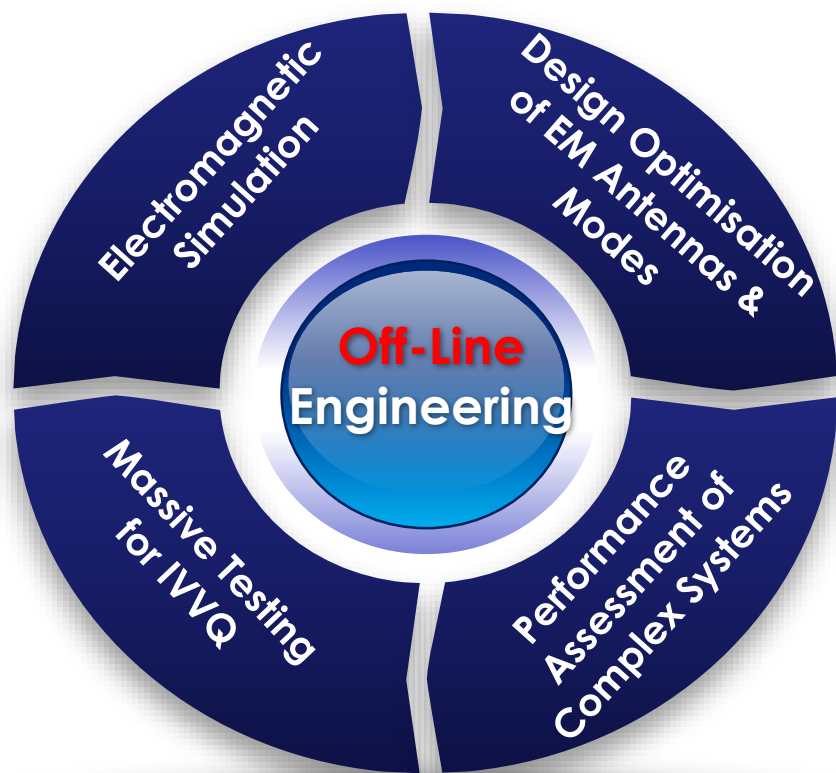
> Challenges

- ▶ Standardization of interfaces (ODSA, UCIE)
- ▶ Low volume interposers (organic L/S 2 μ m)
- ▶ Chiplet assembly and test
- ▶ Computing architecture (determinism)
- ▶ Reliability for Long Mission Profile

THALES involves in this complex subjects



Quantum algorithms use-cases: Engineering, Mission preparation & Operations

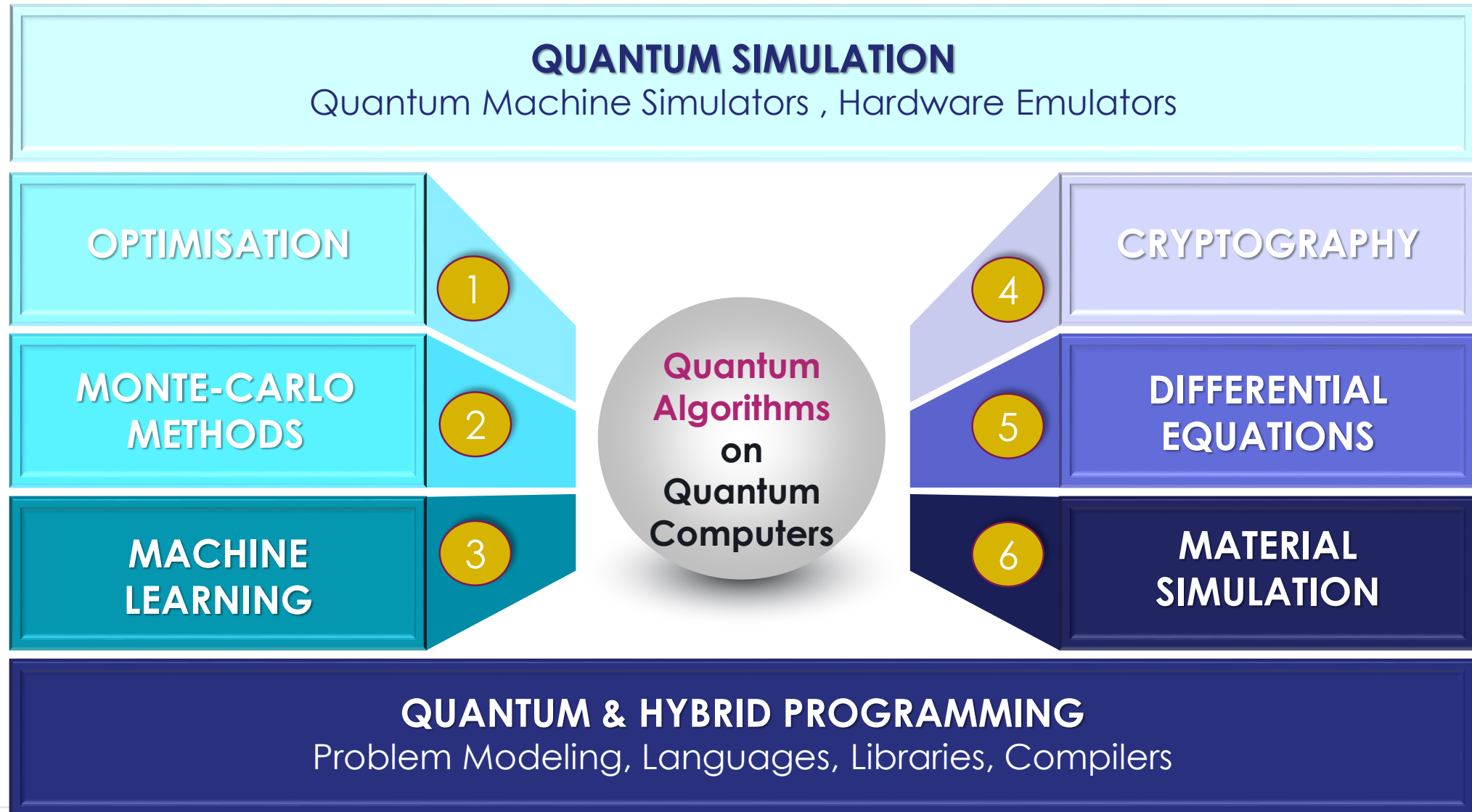


Constraints on Performance
(integrity, accuracy,...)



Constraints on Low Latency
(OODA loop acceleration)

Computational problems solved by Quantum Algorithms





THALES
Building a future we can all trust

Thank you

www.thalesgroup.com